

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/789,914

Filing Date: February 27, 2004

Applicant: Hosomi et al.

Group Art Unit: 1714

Examiner: Kriellion Sanders

Title: Resin Composition, Prepeg, Laminate and Semiconductor Package

Attorney Docket: 2497-000002/CP

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

AMENDMENT UNDER 37 CFR 1.312

Sir:

After the Notice of Allowance dated June 27, 2007 and before payment of the issue fee, please amend the application as follows and consider the remarks set forth below.

Please consider the following:

- Amendments to the Specification;
- Amendments to the Abstract;
- Amendments to the Claims;
- Amendments to the Drawings;
- Remarks**